

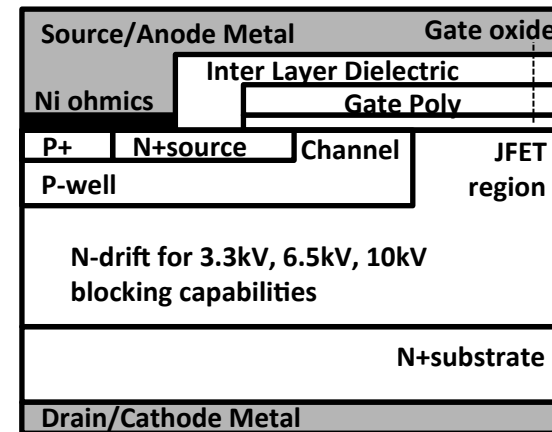
**Project Title:** Development of 3.3kV/6.5kV/10kV SiC MOSFETs, JBS diodes, and JBS diode integrated MOSFETs

**Objectives:** to deliver MV, HV SiC devices

**Major Milestones:** High voltage edge termination technique, Rugged MOSFETs, JBSFET designs

**Significant Equipment Acquisition:** none

**Deliverables:** device design, process flow, and working devices fabricated at Xfab



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**WBG Technology Impact**

1. Supply MV, HV SiC devices to PA members/ 40% reduction in wafer area by adopting one chip integration concept of JBSFET
2. Market segments impacted. Application Spaces: MV drives, Grid application, etc
3. Timeframe for commercialization: BP-3
4. This project will supply MV, HV SiC devices to PA members that are otherwise difficult to attain from commercial vendors.

**More WBG Impact and Additional impacts**

1. Successful demonstration of this project will improve efficiency of MV, HV power converter systems. The proposed JBSFET will reduce the size of a power module and increase the frequency capability.
2. This project will involve two undergrad students, educate one graduate student, one post-doc.
3. Specify TRL level  
 At project start: TRL7  
 Expected at project completion: TRL8